Title (en)

Copper alloy and method of manufacturing the same

Title (de)

Kupferlegierung und Verfahren zu deren Herstellung

Title (fr)

Alliage de cuivre et procédé pour sa fabrication

Publication

EP 1630239 B1 20071017 (EN)

Application

EP 05018715 A 20050829

Priority

JP 2004250938 A 20040830

Abstract (en)

[origin: EP1630239A1] A copper alloy of superior flex durability is provided that is suitable for the conducting members of flexible printed circuits. This is a copper alloy where the integrated intensity ratio I {200} / I {111} found by x-ray diffraction of the rolled surface is 1.5 or less. Examples of its specific chemical composition are: a composition where, in percent by weight, Fe: 0.045-0.095%, P: 0.010-0.030%, the sum of all elements other than Fe, P and Cu is less than 1% and the balance is Cu, and a composition where, in percent by weight, Ni: 0.5-3.0%, Sn: 0.5-2.0%, P: 0.03-0.10%, the sum of all elements other than Ni, Sn, P and Cu is less than 1% and the balance is Cu. The copper alloy has a conductivity of 85% IACS or greater.

IPC 8 full level

C22C 9/00 (2006.01); **C22C 9/02** (2006.01); **C22C 9/06** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP US)

C22C 9/02 (2013.01 - EP US); **C22C 9/06** (2013.01 - EP US); **C22F 1/08** (2013.01 - EP US); **H05K 1/09** (2013.01 - EP US); H05K 2201/0355 (2013.01 - EP US)

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DOCDB simple family (publication)

EP 1630239 A1 20060301; **EP 1630239 B1 20071017**; AT E376074 T1 20071115; CN 100460537 C 20090211; CN 1743481 A 20060308; DE 602005002898 D1 20071129; DE 602005002898 T2 20080207; JP 2006063431 A 20060309; JP 4524471 B2 20100818; US 2006045790 A1 20060302; US 7563408 B2 20090721

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